

## OptiMOS®-P2 Power-Transistor



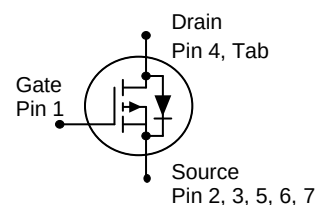
### Features

- P-channel - Normal Level - Enhancement mode
- AEC qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green package (RoHS compliant)
- 100% Avalanche tested

### Product Summary

|              |      |    |
|--------------|------|----|
| $V_{DS}$     | -40  | V  |
| $R_{DS(on)}$ | 2.8  | mΩ |
| $I_D$        | -180 | A  |

PG-TO263-7-3



| Type           | Package      | Marking |
|----------------|--------------|---------|
| IPB180P04P4-03 | PG-TO263-7-3 | 4QP0403 |

Maximum ratings, at  $T_J=25\text{ °C}$ , unless otherwise specified

| Parameter                              | Symbol         | Conditions                                         | Value        | Unit |
|----------------------------------------|----------------|----------------------------------------------------|--------------|------|
| Continuous drain current <sup>1)</sup> | $I_D$          | $T_C=25\text{ °C}$ ,<br>$V_{GS}=-10\text{V}$       | -180         | A    |
|                                        |                | $T_C=100\text{ °C}$ ,<br>$V_{GS}=-10\text{V}^{2)}$ | -131         |      |
| Pulsed drain current <sup>2)</sup>     | $I_{D,pulse}$  | $T_C=25\text{ °C}$                                 | -720         |      |
| Avalanche energy, single pulse         | $E_{AS}$       | $I_D=-90\text{A}$                                  | 90           | mJ   |
| Avalanche current, single pulse        | $I_{AS}$       | -                                                  | -180         | A    |
| Gate source voltage                    | $V_{GS}$       | -                                                  | ±20          | V    |
| Power dissipation                      | $P_{tot}$      | $T_C=25\text{ °C}$                                 | 150          | W    |
| Operating and storage temperature      | $T_J, T_{stg}$ | -                                                  | -55 ... +175 | °C   |
| IEC climatic category; DIN IEC 68-1    | -              | -                                                  | 55/175/56    |      |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

### Thermal characteristics<sup>2)</sup>

|                                                |            |                                              |   |   |     |     |
|------------------------------------------------|------------|----------------------------------------------|---|---|-----|-----|
| Thermal resistance, junction - case            | $R_{thJC}$ | -                                            | - | - | 1.0 | K/W |
| Thermal resistance, junction - ambient, leaded | $R_{thJA}$ | -                                            | - | - | 62  |     |
| SMD version, device on PCB                     | $R_{thJA}$ | minimal footprint                            | - | - | 62  |     |
|                                                |            | 6 cm <sup>2</sup> cooling area <sup>3)</sup> | - | - | 40  |     |

### Electrical characteristics, at $T_j=25^\circ\text{C}$ , unless otherwise specified

#### Static characteristics

|                                  |               |                                                      |      |      |      |            |
|----------------------------------|---------------|------------------------------------------------------|------|------|------|------------|
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=-1mA$                                | -40  | -    | -    | V          |
| Gate threshold voltage           | $V_{GS(th)}$  | $V_{DS}=V_{GS}, I_D=-410\mu A$                       | -2.0 | -3.0 | -4.0 |            |
| Zero gate voltage drain current  | $I_{DSS}$     | $V_{DS}=-32V, V_{GS}=0V, T_j=25^\circ\text{C}$       | -    | -0.1 | -1   | $\mu A$    |
|                                  |               | $V_{DS}=-32V, V_{GS}=0V, T_j=125^\circ\text{C}^{2)}$ | -    | -20  | -200 |            |
| Gate-source leakage current      | $I_{GSS}$     | $V_{GS}=-20V, V_{DS}=0V$                             | -    | -    | -100 | nA         |
| Drain-source on-state resistance | $R_{DS(on)}$  | $V_{GS}=-10V, I_D=-100A$                             | -    | 2.0  | 2.8  | m $\Omega$ |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

### Dynamic characteristics<sup>2)</sup>

|                              |              |                                                                |   |       |       |    |
|------------------------------|--------------|----------------------------------------------------------------|---|-------|-------|----|
| Input capacitance            | $C_{iss}$    | $V_{GS}=0V, V_{DS}=-25V,$<br>$f=1MHz$                          | - | 13570 | 17640 | pF |
| Output capacitance           | $C_{oss}$    |                                                                | - | 4070  | 5290  |    |
| Reverse transfer capacitance | $C_{rss}$    |                                                                | - | 110   | 220   |    |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD}=-20V,$<br>$V_{GS}=-10V, I_D=-180A,$<br>$R_G=3.5\Omega$ | - | 48    | -     | ns |
| Rise time                    | $t_r$        |                                                                | - | 31    | -     |    |
| Turn-off delay time          | $t_{d(off)}$ |                                                                | - | 72    | -     |    |
| Fall time                    | $t_f$        |                                                                | - | 81    | -     |    |

### Gate Charge Characteristics<sup>2)</sup>

|                       |               |                                                               |   |      |     |    |
|-----------------------|---------------|---------------------------------------------------------------|---|------|-----|----|
| Gate to source charge | $Q_{gs}$      | $V_{DD}=-32V,$<br>$I_D=-180A,$<br>$V_{GS}=0 \text{ to } -10V$ | - | 70   | 95  | nC |
| Gate to drain charge  | $Q_{gd}$      |                                                               | - | 35   | 70  |    |
| Gate charge total     | $Q_g$         |                                                               | - | 190  | 250 |    |
| Gate plateau voltage  | $V_{plateau}$ |                                                               | - | -5.2 | -   | V  |

### Reverse Diode

|                                                |               |                                                |   |     |      |    |
|------------------------------------------------|---------------|------------------------------------------------|---|-----|------|----|
| Diode continuous forward current <sup>2)</sup> | $I_S$         | $T_C=25^\circ C$                               | - | -   | -180 | A  |
| Diode pulse current <sup>2)</sup>              | $I_{S,pulse}$ |                                                | - | -   | -720 |    |
| Diode forward voltage                          | $V_{SD}$      | $V_{GS}=0V, I_F=-100A,$<br>$T_J=25^\circ C$    | - | -1  | -1.3 | V  |
| Reverse recovery time <sup>2)</sup>            | $t_{rr}$      | $V_R=-20V, I_F=-50A,$<br>$di_F/dt=-100A/\mu s$ | - | 83  | -    | ns |
| Reverse recovery charge <sup>2)</sup>          | $Q_{rr}$      |                                                | - | 131 | -    | nC |

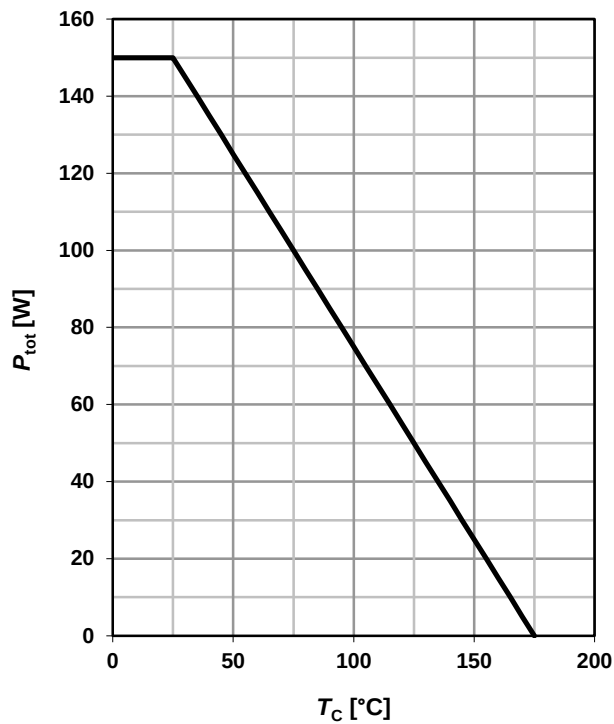
<sup>1)</sup> Current is limited by bondwire; with an  $R_{thJC} = 1.0K/W$  the chip is able to carry -185A at 25°C.

<sup>2)</sup> Defined by design. Not subject to production test.

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

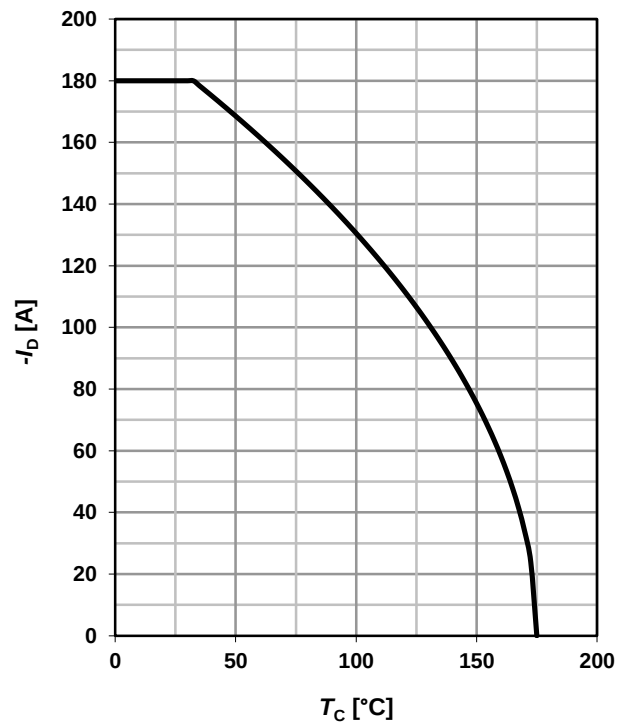
### 1 Power dissipation

$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \leq -6\text{V}$$



### 2 Drain current

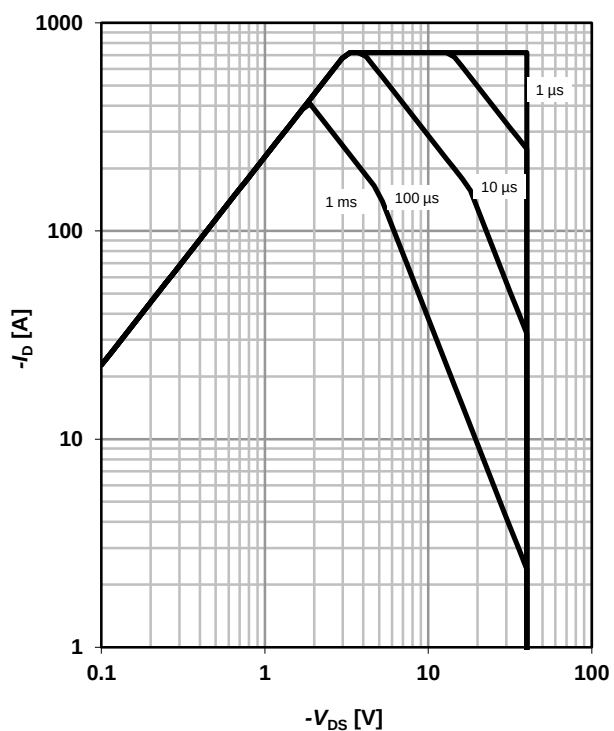
$$I_D = f(T_C); V_{\text{GS}} \leq -6\text{V}; \text{SMD}$$



### 3 Safe operating area

$$I_D = f(V_{\text{DS}}); T_C = 25^{\circ}\text{C}; D = 0; \text{SMD}$$

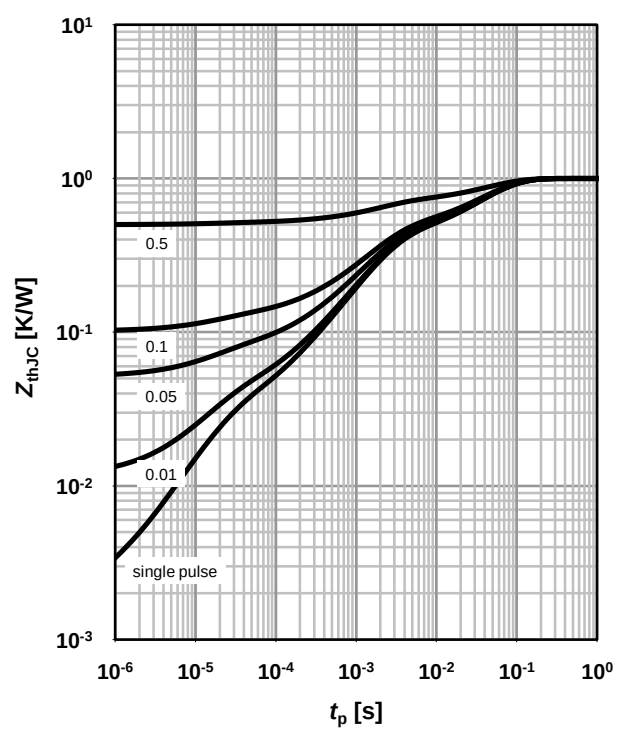
parameter:  $t_p$



### 4 Max. transient thermal impedance

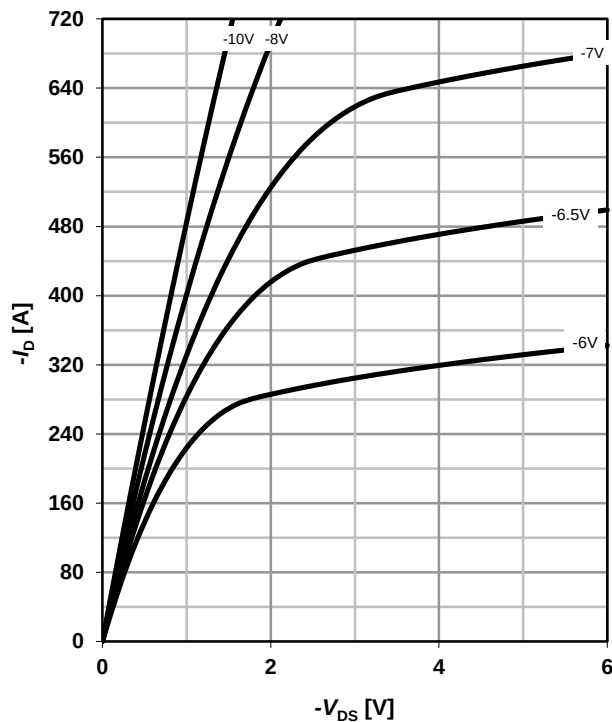
$$Z_{\text{thJC}} = f(t_p)$$

parameter:  $D = t_p/T$



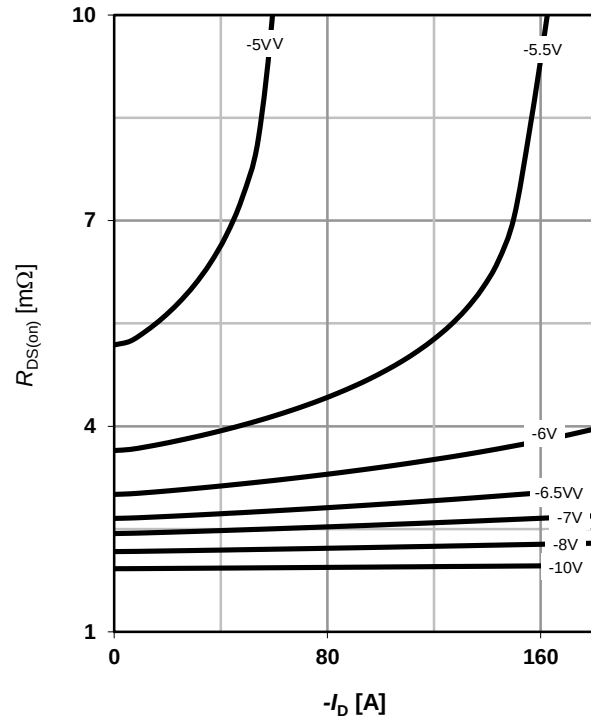
## 5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25\text{ °C}; \text{SMD}$ 

parameter:  $V_{GS}$ 


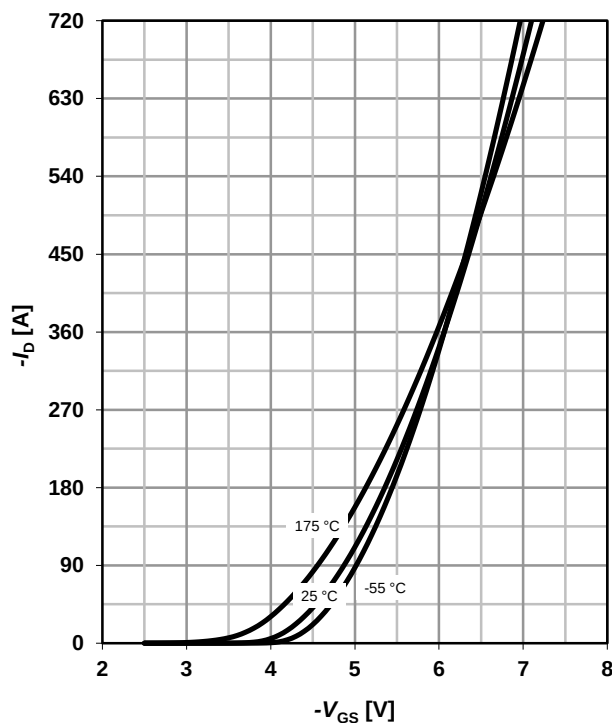
## 6 Typ. drain-source on-state resistance

 $R_{DS(on)} = f(I_D); T_j = 25\text{ °C}; \text{SMD}$ 

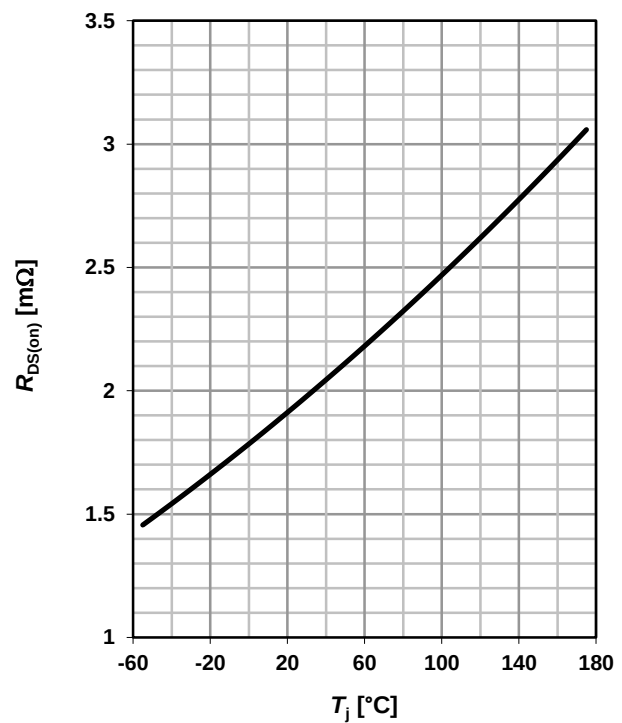
parameter:  $V_{GS}$ 


## 7 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} = -6V$ 

parameter:  $T_j$ 


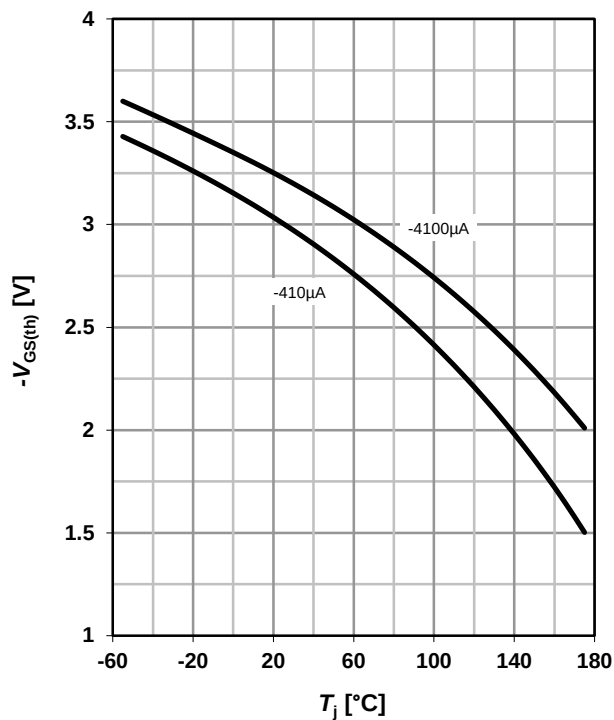
## 8 Typ. drain-source on-state resistance

 $R_{DS(on)} = f(T_j); I_D = -100\text{ A}; V_{GS} = -10\text{ V}; \text{SMD}$ 


## 9 Typ. gate threshold voltage

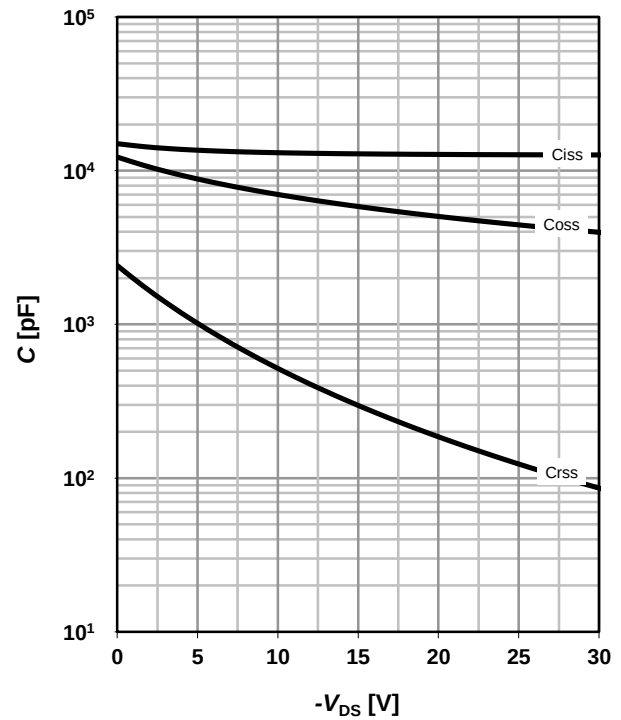
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

parameter:  $I_D$



## 10 Typ. capacitances

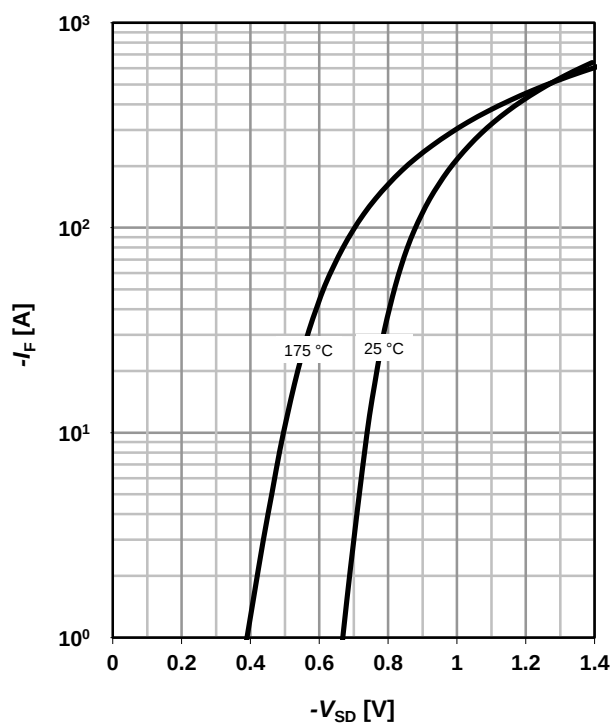
$$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$$



## 11 Typical forward diode characteristics

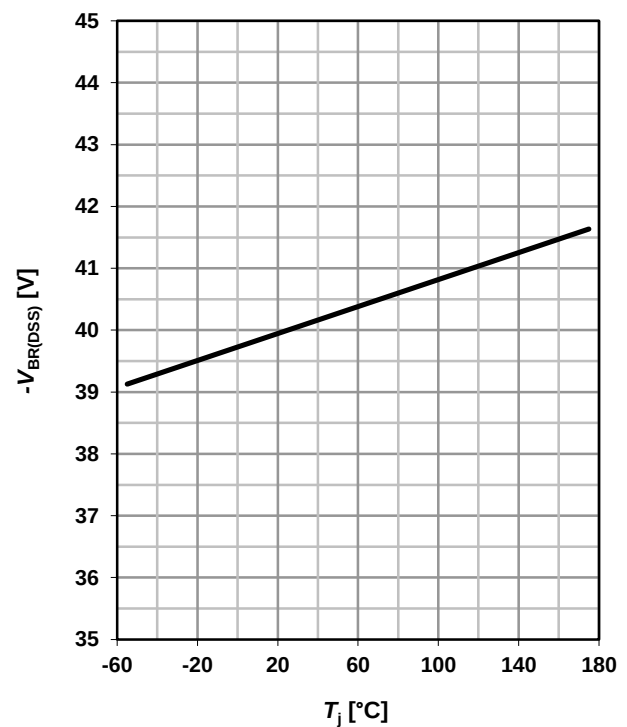
$$I_F = f(V_{SD})$$

parameter:  $T_j$



## 12 Drain-source breakdown voltage

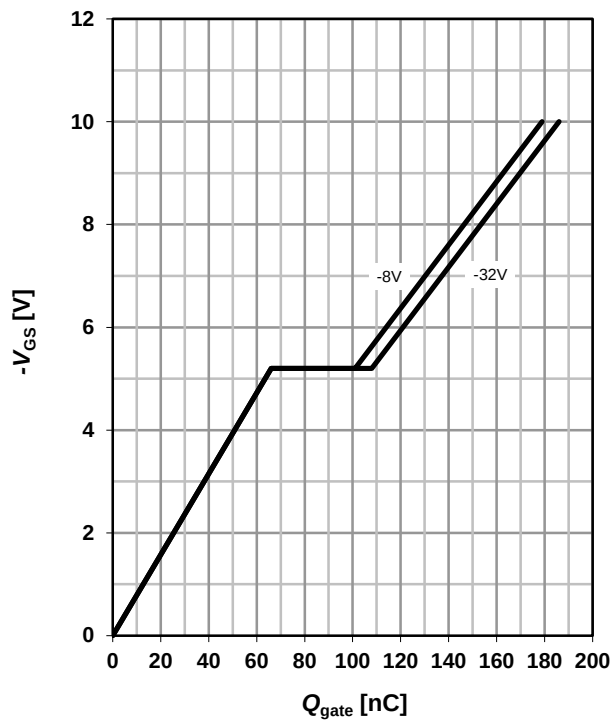
$$V_{BR(DSS)} = f(T_j); I_D = -1 mA$$



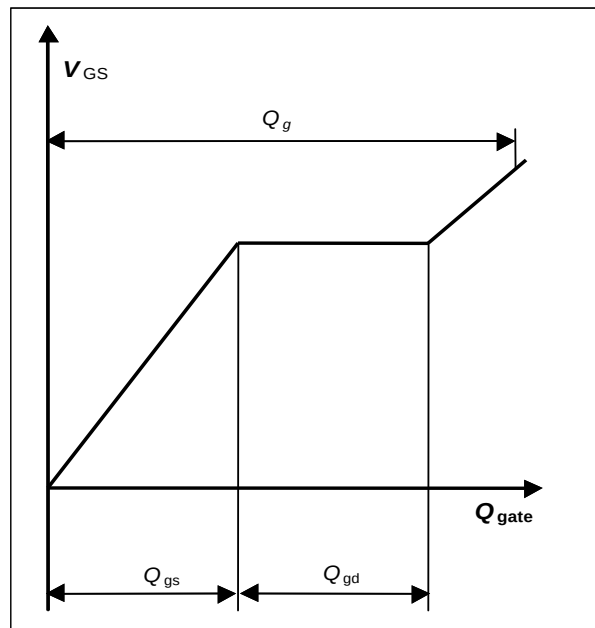
### 13 Typ. gate charge

$V_{GS} = f(Q_{gate}); I_D = -180 \text{ A pulsed}$

parameter:  $V_{DD}$



### 14 Gate charge waveforms



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## Revision History

| Version | Date       | Changes                        |
|---------|------------|--------------------------------|
| 1.0     | 27.04.2011 | Final Data Sheet               |
| 1.1     | 18.01.2018 | Condition for Avalanche energy |

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